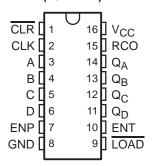
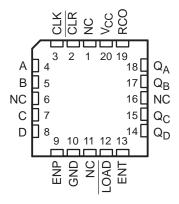
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical  $t_{pd} = 14 \text{ ns}$
- ±4-mA Output Drive at 5 V

SN54HC161...J OR W PACKAGE SN74HC161 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Input Current of 1 µA Max
- Internal Look-Ahead for Fast Counting
- **Carry Output for n-Bit Cascading**
- **Synchronous Counting**
- Synchronously Programmable

SN54HC161 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. The 'HC161 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

#### ORDERING INFORMATION

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC161N	SN74HC161N
	Tube of 40 SN74HC161D			
	SOIC - D Reel of 2500 SN74HC161DR   Reel of 250 SN74HC161DT   SOP - NS Reel of 2000 SN74HC161NSR		HC161	
4000 1- 0500			SN74HC161DT	
-40°C to 85°C			SN74HC161NSR	HC161
		Tube of 90	SN74HC161PW	
	TSSOP - PW	Reel of 2000	SN74HC161PWR	HC161
		Reel of 250	SN74HC161PWT	
	CDIP – J	Tube of 25	SNJ54HC161J	SNJ54HC161J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC161W	SNJ54HC161W
	LCCC – FK	Tube of 55	SNJ54HC161FK	SNJ54HC161FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of



## SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

#### description/ordering information (continued)

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

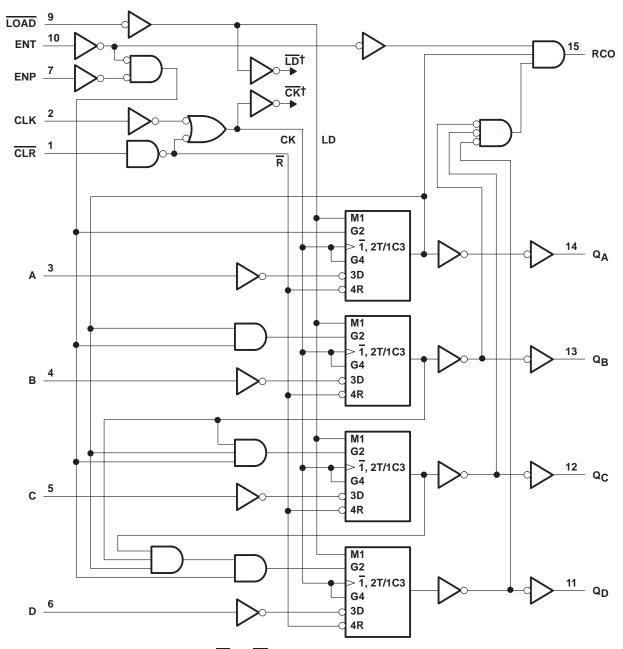
The clear function for the 'HC161 devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.



## logic diagram (positive logic)

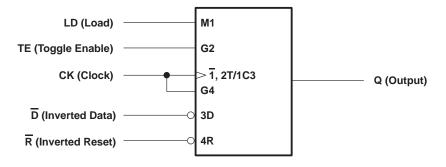


<sup>†</sup> For simplicity, routing of complementary signals  $\overline{LD}$  and  $\overline{CK}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

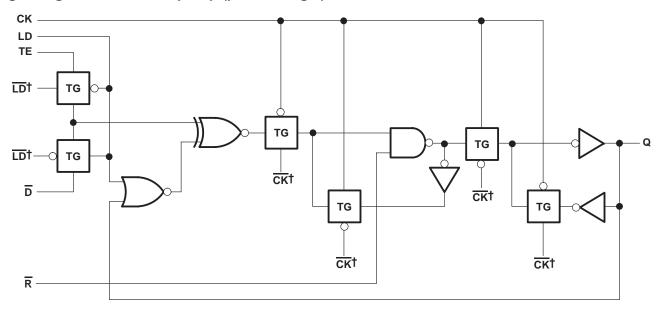
Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## logic symbol, each D/T flip-flop



## logic diagram, each D/T flip-flop (positive logic)

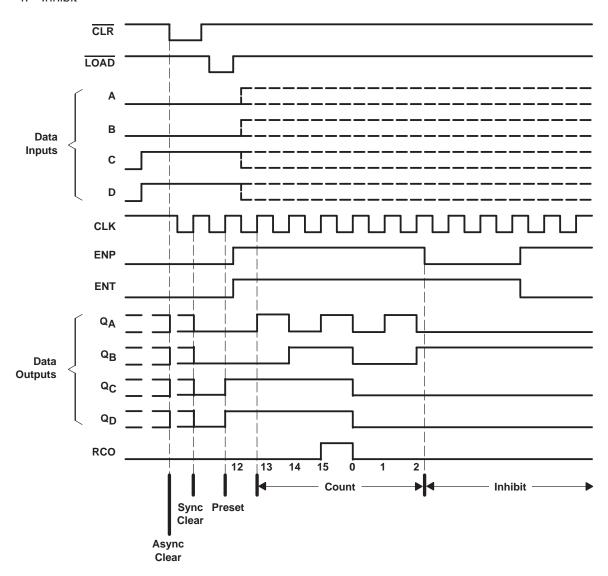


 $<sup>^{\</sup>dagger}$  The origins of  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  are shown in the logic diagram of the overall device.

## typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



## SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>		-0.5	V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (se	ee Note 1)		±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	c) (see Note 1)		±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	·		±25 mA
Continuous current through V <sub>CC</sub> or GND			±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	D package		73°C/W
	N package		67°C/W
	NS package		64°C/W
	PW package	1	108°C/W
Storage temperature range, T <sub>stg</sub>		65°C 1	to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions (see Note 3)

			SN	154HC16	61	SN	174HC16	61	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
٧ <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V <sub>CC</sub> = 2 V			0.5			0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V
		V <sub>CC</sub> = 6 V			1.8			1.8	
٧ <sub>I</sub>	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V			1000			1000	
Δt/Δv‡	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		V <sub>CC</sub> = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>‡</sup> If this device is used in the threshold region (from V<sub>IL</sub>max = 0.5 V to V<sub>IH</sub>min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t<sub>t</sub> = 1000 ns and V<sub>CC</sub> = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	MOITIONS	.,	Т	A = 25°C	;	SN54H	IC161	SN74H	C161	
PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VoL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci		_	2 V to 6 V		3	10		10	_	10	pF

## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			1,,	T <sub>A</sub> =	25°C	SN54H	IC161	SN74H	IC161	
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		
	Pulse duration		6 V	14		20		17		20
t <sub>W</sub>	Pulse duration		2 V	80		120		100		ns
		CLR low	4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	150		225		190		
		A, B, C, or D	4.5 V	30		45		38		
			6 V	26		38		32		
			2 V	135		205		170		
		LOAD low	4.5 V	27		41		34		
	Catura tima a historia CLIVA		6 V	23		35		29		
t <sub>su</sub>	Setup time before CLK↑		2 V	170		255		215		ns
		ENP, ENT	4.5 V	34		51		43		
			6 V	29		43		37		
			2 V	125		190		155		
		CLR inactive	4.5 V	25		38		31		
			6 V	21		32		26		
		2 V	0		0		0			
t <sub>h</sub> Hold time, all synchronous inputs after CLK↑	4.5 V	0		0		0		ns		
		6 V	0		0		0			

## SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

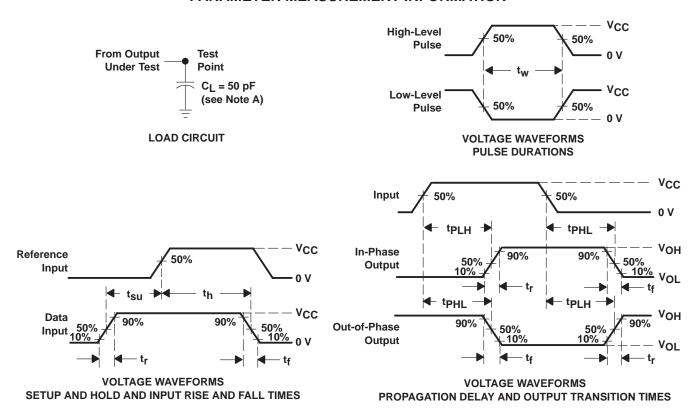
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то		T,	Δ = 25°C	;	SN54F	IC161	SN74F	IC161			
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V	6	14		4.2		5				
f <sub>max</sub>			4.5 V	31	40		21		25		MHz		
			6 V	36	44		25		29				
			2 V		83	215		325		270			
		RCO	4.5 V		24	43		65		54			
	CLK		6 V		20	37		55		46			
	CLK		2 V		80	205		310		255			
<sup>t</sup> pd		Any Q	4.5 V		25	41		62		51	ns		
	·		6 V		21	35		53		43			
			2 V		62	195		295		245			
	ENT	RCO	4.5 V		17	39		59		49			
			6 V		14	33		50		42			
			2 V		105	210		315		265			
		Any Q	4.5 V		21	42		63		53			
t	CLR		6 V		18	36		54		45	ns		
<sup>t</sup> PHL	CLK		2 V		110	220		330		275	115		
		RCO	4.5 V		22	44		66		55			
			6 V		19	37		56		47			
			2 V		38	75		110		95			
t <sub>t</sub>		Any 4	Any 4	Any	4.5 V		8	15		22		19	ns
	ν,		6 V		6	13		19		16			

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	60	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. For clock inputs,  $f_{\text{max}}$  is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

SCLS297D - JANUARY 1996 - REVISED SEPTEMBER 2003

#### APPLICATION INFORMATION

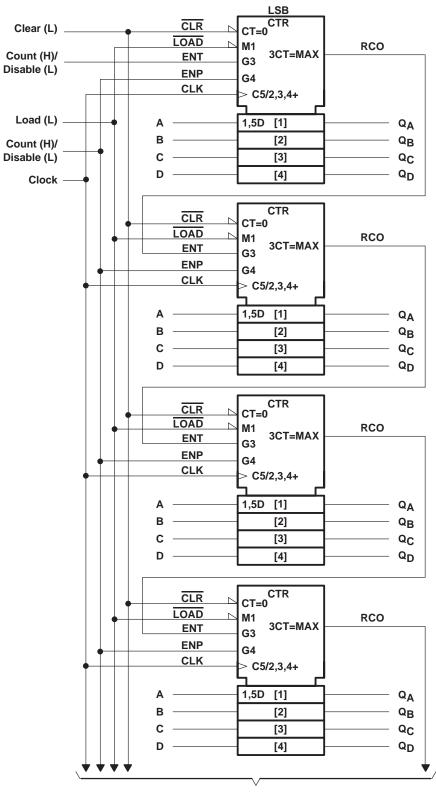
#### n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The 'HC161 devices count in binary. Virtually any count mode (modulo-N, N<sub>1</sub>-to-N<sub>2</sub>, N<sub>1</sub>-to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at  $25^{\circ}$ C and  $4.5\text{-V}\ V_{CC}$ ). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).



## **APPLICATION INFORMATION**



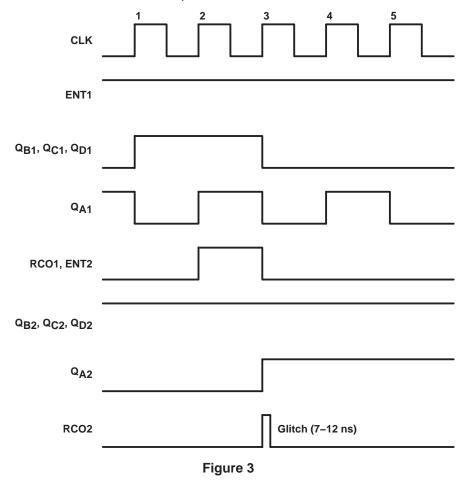
To More-Significant Stages

Figure 2



#### **APPLICATION INFORMATION**

The glitch on RCO is caused because the propagation delay of the rising edge of  $Q_A$  of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT,  $Q_A$ ,  $Q_B$ ,  $Q_C$ , and  $Q_D$  (ENT  $\times$   $Q_A \times Q_B \times Q_C \times Q_D$ ). The resulting glitch is about 7–12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages.  $Q_B$ ,  $Q_C$ , and  $Q_D$  of the first and second stage are at logic one, and  $Q_A$  of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse,  $Q_A$  and RCO of the first stage go high. On the rising edge of the third clock pulse,  $Q_A$  and RCO of the first stage return to a low level, and  $Q_A$  of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.



The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration ( $t_g$ ). In other words,  $t_{max} = 1/(t_{pd} \text{ CLK-to-RCO} + t_g)$ . For example, at 25°C at 4.5-V V<sub>CC</sub>, the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the  $t_{clock}$ ,  $t_{w}$ , and  $t_{max}$  specifications for applications that use more than two 'HC161 devices cascaded together.

#### **APPLICATION INFORMATION**

## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		.,	T <sub>A</sub> = 2	25°C	SN54F	IC161	SN74H	IC161	
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		3.6		2.5		2.9	
fclock	Clock frequency	4.5 V		18		12		14	MHz
		6 V		21		14		17	
		2 V	140		200		170		
t <sub>W</sub>	Pulse duration, CLK high or low	4.5 V	28		40		36		ns
		6 V	24		36		30		

## switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Note 4)

	FROM	то	.,	$T_A = 2$	25°C	SN54HC161		SN74HC161		
PARAMETER	(INPUT)	(OUTPUT)	VCC		MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	3.6		2.5		2.9		
f <sub>max</sub>			4.5 V	18		12		14		MHz
			6 V	21		14		17		

NOTE 4: These limits apply only to applications that use more than two 'HC161 devices cascaded together.

If the 'HC161 devices are used as a single unit, or only two cascaded together, then the maximum clock frequency that the device can use is not limited because of the glitch. In these situations, the device can be operated at the maximum specifications.

A glitch can appear on RCO of a single 'HC161 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input except an ENT of another cascaded 'HC161 device must take this into consideration.



## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-8407501VEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8407501VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
84075012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8407501EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8407501FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/66302BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/66302BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54HC161J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC161D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DBR	OBSOLETE	SSOP	DB	16		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC161N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74HC161NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC161NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161NSRE4	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM



#### PACKAGE OPTION ADDENDUM

9-Oct-2007

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
SN74HC161PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC161FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC161J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54HC161W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



i.com 19-Mar-2008

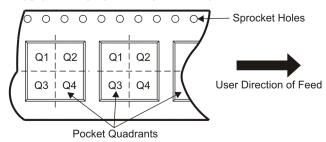
#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC161DBR	SSOP	DB	16	0	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74HC161DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC161NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC161PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1





\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC161DBR	SSOP	DB	16	0	346.0	346.0	33.0
SN74HC161DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC161NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74HC161PWR	TSSOP	PW	16	2000	346.0	346.0	29.0

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

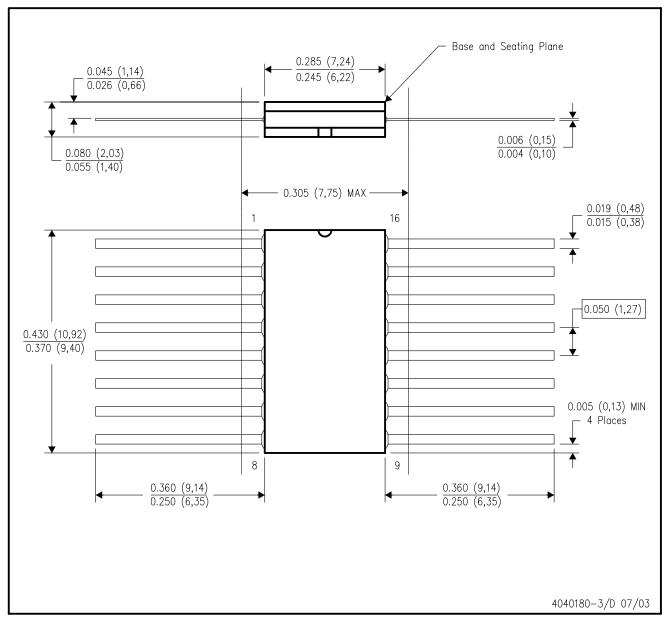
## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK

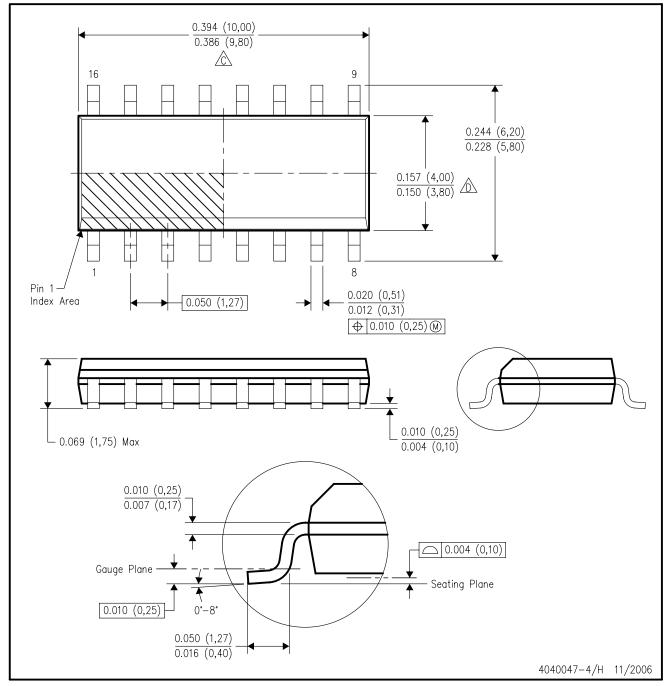


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated